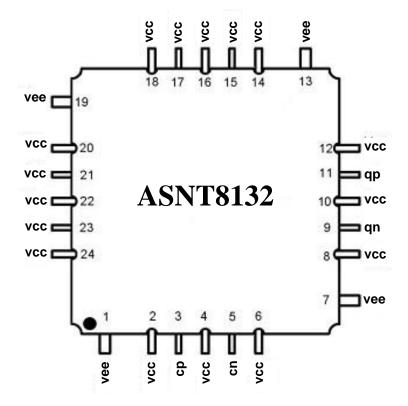
ASNT8132-KMC DC-54*GHz* Broadband Clock Divider by 2

- High speed broadband clock divider by 2
- Exhibits low jitter and limited temperature variation over industrial temperature range
- Fully differential CML input interface
- Fully differential CML output interface with 400mV situale-ended swings.
- Single +3.3V or -3.3V power supply
- Power consumption: 630mW
- Fabricated in SiGe for high performance, yield, and reliability
- Custom CQFP 24-pin package



DESCRIPTION

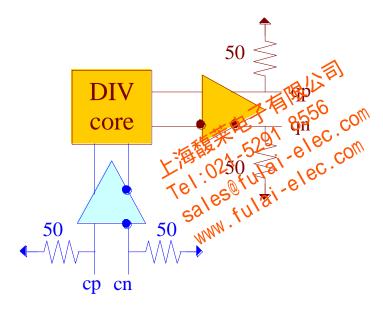


Fig. 1. Functional Block Diagram

The temperature stable ASNT8132-KMC SiGe IC provides broadband clock divide-by-2 functionality, and is intended for use in high-speed measurement / test equipment. The IC shown in Fig. 1 can process a high-speed clock input signal cp/cn and deliver a high-speed clock output signal qp/qn with 50% duty cycle.

The part's I/O's support the CML logic interface with on chip 50*Ohm* termination to vcc and may be used differentially, AC/DC coupled, single-ended, or in any combination (see also POWER SUPPLY CONFIGURATION). In the DC-coupling mode, the input signal's common mode voltage should comply with the specifications shown in ELECTRICAL CHARACTERISTICS. In the AC-coupling mode, the input termination provides the required common mode voltage automatically. The differential DC signaling mode is recommended for optimal performance.

POWER SUPPLY CONFIGURATION

The part can operate with either a negative supply (vcc = 0.0V = ground and vee = -3.3V), or a positive supply (vcc = +3.3V and vee = 0.0V = ground). In case of a positive supply, all I/Os need AC termination when connected to any devices with 50Ohm termination to ground. Different PCB layouts will be needed for each different power supply combination.

All the characteristics detailed below assume vcc = 0.0V and vee = -3.3V.



ABSOLUTE MAXIMUM RATINGS

Caution: Exceeding the absolute maximum ratings shown in Table 1 may cause damage to this product and/or lead to reduced reliability. Functional performance is specified over the recommended operating conditions for power supply and temperature only. AC and DC device characteristics at or beyond the absolute maximum ratings are not assumed or implied. All min and max voltage limits are referenced to ground.

Table 1. Absolute Maximum Retings

Parameter	Min - A	Max.e V	co ^m Units
Supply Voltage (vee)	2,.0	1, 1, 13.6 1 6C.	V
Power Consumption	16/.	36 ⁰ 0:36 ⁰	W
RF Input Voltage Swing (SE)	68/	4019.0	V
Case Temperature	Wa.	49 0	°C
Storage Temperature	-40	+100	°C
Operational Humidity	10	98	%
Storage Humidity	10	98	%

TERMINAL FUNCTIONS

TI	ERMIN	AL	DESCRIPTION				
Name	No.	Type					
	High-Speed I/Os						
ср	3	CML	Differential clock inputs with internal SE 50 <i>Ohm</i> termination				
cn	5	input	to VCC				
qp	11	CML	Differential clock outputs with internal SE 50 <i>Ohm</i> termination				
qn	9	output	to vcc. Require external SE 50 <i>Ohm</i> termination to vcc				
	Supply and Termination Voltages						
Name	Name Description			Pin Number			
vcc	Positive power supply (+3.3 <i>V</i> or 0)		er supply (+3.3 <i>V</i> or 0)	2, 4, 6, 8, 10, 12, 14, 15, 16, 17, 18,			
				20, 21, 22, 23, 24			
vee	Negative power supply (0V or -3.3V)		er supply $(0V \text{ or } -3.3V)$	1, 7, 13, 19			



ELECTRICAL CHARACTERISTICS

PARAMETER	MIN	TYP	MAX	UNIT	COMMENTS
General Parameters					
vee	-3.1	-3.3	-3.5	V	±6%
vcc		0.0		V	Toternal ground
<i>I</i> vee		190		mA 💉	# 859 COM
Power consumption		630		nin	5291 e1ec 0111
Junction temperature	-40	25	125	Cita Col	1,101,00.00
HS Input Clock (cp/cn)					
Frequency	DC		54	GHIS	11/31
Swing	0.2		1.0	Vann	Differential or SE, p-p
CM Voltage Level	vcc-0.8		VCC	Mag	Must match for both inputs
HS Output Clock (qp/qn)					
Frequency	DC		27	GHz	
Logic "1" level		VCC		V	
Logic "0" level		vcc-0.4		V	With external 50 <i>Ohm</i> DC termination
Rise/Fall times	4	5	7	ps	20%-80%
Output Jitter			1	ps	Peak-to-peak
Duty cycle	45	50	55	%	

PACKAGE INFORMATION

The chip die is housed in a custom 24-pin CQFP package shown in Fig. 2. Even though the package provides a center heat slug located on the back side of the package to be used for heat dissipation, ADSANTEC does **NOT** recommend for this section to be soldered to the board. If the customer wishes to solder it, it should be connected to the **vcc** plain that is ground for the negative supply or power for the positive supply.

The part's identification label is ASNT8132-KMC. The first 8 characters of the name before the dash identify the bare die including general circuit family, fabrication technology, specific circuit type, and part version while the 3 characters after the dash represent the package's manufacturer, type, and pin out count.

The IC complies with the Restriction of Hazardous Substances (RoHS) per EU 2002/95/EC for all 6 substances.

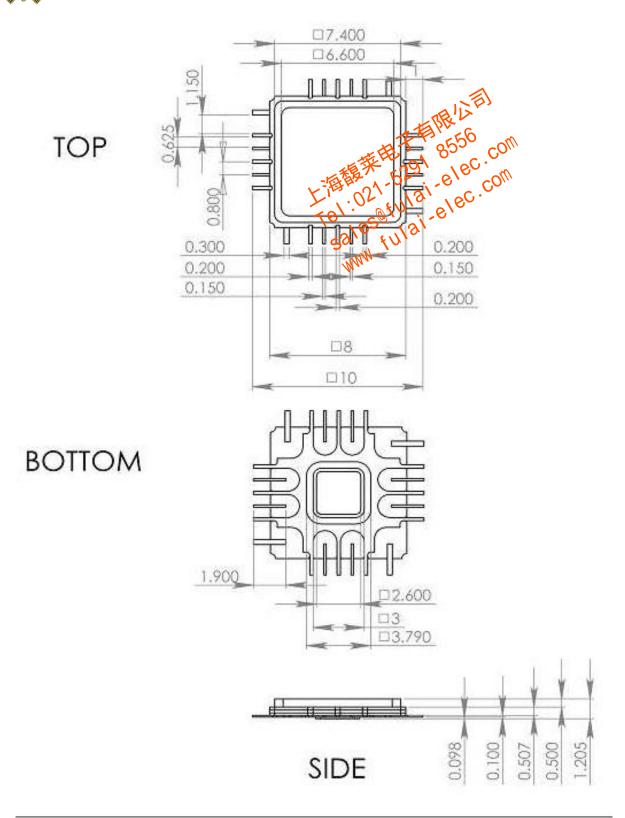


Fig. 2. CQFP 24-Pin Package Drawing (All Dimensions in mm)



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REVISION HISTORY

Revision	Date	Changes		
1.2.1	10-2014	Corrected power consumption		
1.1.1	03-2014	Corrected maximum speed		
1.0.1	12-2013	First release	>	

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